

Crystal-lessTM Configurable Two-Output Clock Generator

Features

- · Two Simultaneous CMOS Outputs
 - Output 1 Range: 2.3 MHz to 170 MHz
- Output 2 Range: 2.3 MHz to 170 MHz
- Low RMS Phase Jitter: <1 ps (typ.)
- High Stability: ±25 ppm, ±50 ppm
- · Wide Temperature Range
 - Automotive: -40°C to +125°C
 - Ext. Industrial -40°C to +105°C
 - Industrial -40°C to +85°C
 - Ext. Commercial -20°C to +70°C
- High Supply Noise Rejection: -50 dBc
- · High Shock and Vibration Immunity
 - Qualified to MIL-STD-883
- · High Reliability
 - 20x higher MTBF than crystal-based clock generator designs
- · Supply Range of 2.25V to 3.6V
- · Lead Free and RoHS-Compliant

Applications

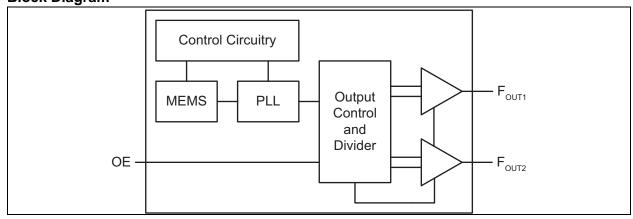
- · Consumer Electronics
- · Camera and Imaging Modules
- · Home Automation
- · Industrial and Power Conversion
- Mobile Communications, Internet, and Sensor Devices
- · Solid State, Hard Drive, and Flash Drive Storage

General Description

The DSC2311 is a crystal-less™ clock generator that is factory-configurable to simultaneously output two separate frequencies from 2.3 MHz to 170 MHz. The clock generator uses proven silicon MEMS technology to provide low jitter and high frequency stability across a wide range of supply voltages and temperatures. By eliminating the external quartz crystal, crystal-less clock generators significantly enhance reliability and accelerate product development, while meeting stringent clock performance criteria for a variety of consumer electronics, communications, and storage applications.

DSC2311 has an Output Enable/Disable feature that allows it to disable the outputs when OE is low. The device is available in a space-saving 6-pin 2.5 mm x 2.0 mm crystal-less VDFN package that uses only a single external bypass capacitor. This requires a PCB footprint equivalent to that of a 1.0 mm x 1.0 mm crystal-based clock generator.

Block Diagram



1.0 ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings †

| Supply Voltage | –0.3V to +4.0V |
|----------------------|-------------------------------|
| Input Voltage | 0.3V to V _{DD} +0.3V |
| ESD Protection (HBM) | |
| ESD Protection (CDM) | 1.5 kV |

† Notice: Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operational sections of this specification is not intended. Exposure to maximum rating conditions for extended periods may affect device reliability.

ELECTRICAL CHARACTERISTICS

Specifications: V_{DD} = 3.3V; T_A = +25°C unless otherwise specified.

| Parameters | Sym. | Min. | Тур. | Max. | Units | Conditions |
|------------------------------|-------------------|------------------------|------|------------------------|-------|---|
| Supply Voltage (Note 1) | V_{DD} | 2.25 | 1 | 3.6 | ٧ | _ |
| Supply Current (Note 2) | I _{DD} | _ | 21 | 23 | mA | EN pin low. All outputs disabled. |
| | | _ | - | ±25 | | Includes frequency |
| Frequency Stability (Note 3) | Δf | _ | | ±50 | ppm | variations due to initial tolerance, temperature, and power supply voltage. |
| Aging | Δf | _ | _ | ±5 | ppm | One year at +25°C |
| Start-up Time (Note 4) | t _{SU} | _ | | 5 | ms | T = +25°C |
| Input Logic Levels | V_{IH} | 0.75 x V _{DD} | _ | _ | V | Input logic high |
| input Logic Levels | V_{IL} | _ | _ | 0.25 x V _{DD} | V | Input logic low |
| Output Disable Time | t _{DA} | _ | 1 | 5 | ns | _ |
| Output Enable Time | t _{EN} | _ | - | 20 | ns | _ |
| Pull-Up Resistor (Note 2) | | _ | 40 | _ | kΩ | Pull-up exists on all digital IO |
| Output Logic Lovele | V_{OH} | 0.9 x V _{DD} | 1 | _ | V | Output logic high, I = ±6 mA |
| Output Logic Levels | V_{OL} | _ | 1 | 0.1 x V _{DD} | ٧ | Output logic low, I = ±6 mA |
| Output Transition Time | t _R | _ | 1.1 | 2.0 | no | Rise time. 20% to 80%; C _L = 15 pF |
| Output Transition Time | t _F | _ | 1.4 | 2.0 | ns | Fall time. 20% to 80%; C _L = 15 pF |
| Frequency | | 2.3 | | 170 | | Commercial/Industrial temp. range |
| | cy f ₀ | 3.3 | | 100 | MHz | Automotive temp. range |
| | | 3.3 | _ | 170 | | Extended Industrial temp. range |

- **Note 1:** Pin 4 V_{DD} should be filtered with a 0.01 μF capacitor.
 - 2: Output is enabled if Enable pad is floated or not connected. Operating current = disabled current + ΔI_{DD} from F_{OUT1} + ΔI_{DD} from F_{OUT2} . See Current Consumption graph for more information.
 - **3:** For other ppm stabilities, please contact the factory.
 - **4:** t_{SU} is time to 100 ppm stable output frequency after V_{DD} is applied and outputs are enabled.
 - 5: Period jitter includes crosstalk from adjacent output.

ELECTRICAL CHARACTERISTICS (CONTINUED)

Specifications: V_{DD} = 3.3V; T_A = +25°C unless otherwise specified.

| Parameters | Sym. | Min. | Тур. | Max. | Units | Conditions |
|------------------------|-----------------|------|------|------|-------------------|--|
| Output Duty Cycle | SYM | 45 | _ | 55 | % | _ |
| Period Jitter (Note 5) | J_{PER} | _ | 3 | 1 | ps _{RMS} | F _{O1} = F _{O2} = 25 MHz |
| | | _ | 0.3 | _ | ps _{RMS} | 200 kHz to 20 MHz @ 25 MHz |
| Integrated Phase Noise | J _{CC} | _ | 0.38 | _ | | 100 kHz to 20 MHz @ 25 MHz |
| | | _ | 1.7 | 2 | | 12 kHz to 20 MHz @ 25 MHz |

- **Note 1:** Pin 4 V_{DD} should be filtered with a 0.01 μF capacitor.
 - 2: Output is enabled if Enable pad is floated or not connected. Operating current = disabled current + ΔI_{DD} from F_{OUT1} + ΔI_{DD} from F_{OUT2} . See Current Consumption graph for more information.
 - 3: For other ppm stabilities, please contact the factory.
 - **4:** t_{SU} is time to 100 ppm stable output frequency after V_{DD} is applied and outputs are enabled.
 - **5:** Period jitter includes crosstalk from adjacent output.

TEMPERATURE SPECIFICATIONS (Note 1)

| Parameters | Sym. | Min. | Тур. | Max. | Units | Conditions | |
|---------------------------------|----------------|------|------|------|-------|-------------------|--|
| Temperature Ranges | | | | | | | |
| | T _A | -20 | _ | +70 | °C | Ordering Option E | |
| Operating Temperature Range (T) | T _A | -40 | _ | +85 | °C | Ordering Option I | |
| | T _A | -40 | _ | +105 | °C | Ordering Option L | |
| | T _A | -40 | _ | +125 | °C | Ordering Option M | |
| Junction Temperature | TJ | _ | _ | +150 | °C | _ | |
| Storage Temperature Range | T _S | -40 | _ | +150 | °C | _ | |
| Soldering Temperature Range | _ | _ | _ | +260 | °C | 40 sec. max. | |

Note 1: The maximum allowable power dissipation is a function of ambient temperature, the maximum allowable junction temperature, and the thermal resistance from junction to air (i.e., T_A, T_J, θ_{JA}). Exceeding the maximum allowable power dissipation will cause the device operating junction temperature to exceed the maximum +125°C rating. Sustained junction temperatures above +125°C can impact the device reliability.

2.0 PIN DESCRIPTIONS

The descriptions of the pins are listed in Table 2-1.

TABLE 2-1: PIN FUNCTION TABLE

| Pin Number | Pin Name | Description |
|------------|----------|---------------------------------------|
| 1 | ENABLE | Output Enable for both CLK0 and CLK1. |
| 2 | N/C | Do not connect. |
| 3 | GROUND | Ground. |
| 4 | CLK0 | Clock Output 0 (CMOS). |
| 5 | CLK1 | Clock Output 1 (CMOS). |
| 6 | VDD | Supply Voltage. |

3.0 OUTPUT WAVEFORM

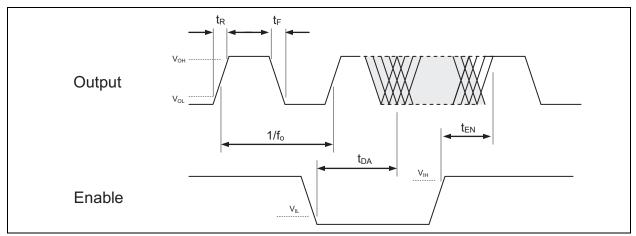


FIGURE 3-1: OE Function and Output Waveform: LVCMOS.

4.0 CURRENT CONSUMPTION

Total Current = Disabled Current + $\Delta I_{DD} F_{OUT1} + \Delta I_{DD} F_{OUT2}$

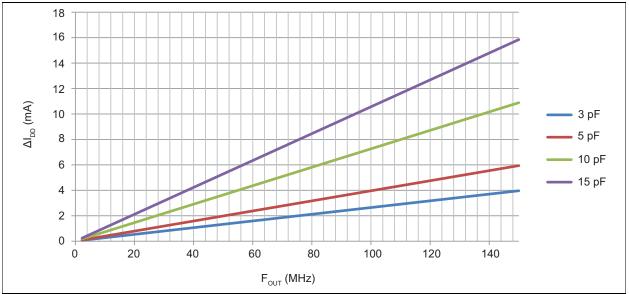
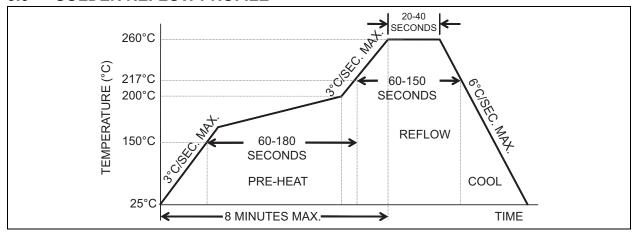


FIGURE 4-1: ΔI_{DD} / Output vs. Frequency and Load @ 3.3V V_{DD}

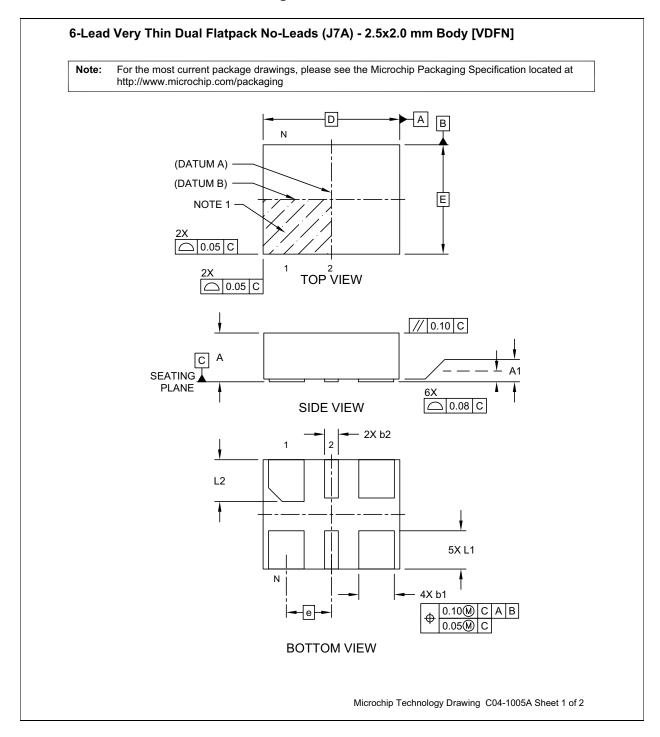
5.0 SOLDER REFLOW PROFILE



| 6-PIN QFN MSL 1 @ 260°C refer to JSTD-020C | | | | |
|--|----------------|--|--|--|
| Ramp-Up Rate (200°C to Peak Temp) | 3°C/sec. max. | | | |
| Preheat Time 150°C to 200°C | 60-180 sec. | | | |
| Time Maintained above 217°C | 60-150 sec. | | | |
| Peak Temperature | 255°C to 260°C | | | |
| Time within 5°C of Actual Peak | 20-40 sec. | | | |
| Ramp-Down Rate | 6°C/sec. max. | | | |
| Time 25°C to Peak Temperature | 8 minutes max. | | | |

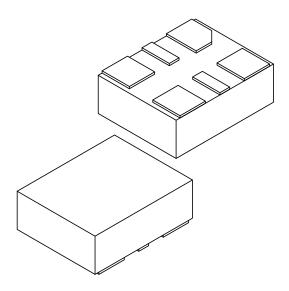
6.0 PACKAGE MARKING INFORMATION

6-Lead VDFN 2.5 mm x 2.0 mm Package Outline and Recommended Land Pattern



6-Lead Very Thin Dual Flatpack No-Leads (J7A) - 2.5x2.0 mm Body [VDFN]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



| | Units | MILLIMETERS | | | |
|---------------------|--------|-------------|-------|-------|--|
| Dimension | Limits | MIN | NOM | MAX | |
| Number of Terminals | N | 6 | | | |
| Pitch | е | 0.825 BSC | | | |
| Overall Height | Α | 0.80 | 0.85 | 0.90 | |
| Standoff | A1 | 0.00 | 0.02 | 0.05 | |
| Overall Length | D | 2.50 BSC | | | |
| Overall Width | Е | 2.00 BSC | | | |
| Terminal Width | b1 | 0.60 | 0.65 | 0.70 | |
| Terminal Width | b2 | 0.20 | 0.25 | 0.30 | |
| Terminal Length | L1 | 0.60 | 0.70 | 0.80 | |
| Terminal Length | L2 | 0.665 | 0.765 | 0.865 | |

Notes:

- 1. Pin 1 visual index feature may vary, but must be located within the hatched area.
- 2. Package is saw singulated
- 3. Dimensioning and tolerancing per ASME Y14.5M

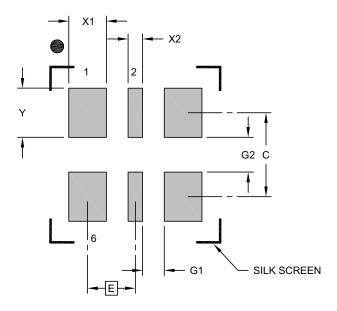
BSC: Basic Dimension. Theoretically exact value shown without tolerances.

REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-1005A Sheet 2 of 2

6-Lead Very Thin Dual Flatpack No-Leads (J7A) - 2.5x2.0 mm Body [VDFN]

For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

| | Units | | MILLIMETERS | | |
|-----------------------------|-------|-----------|-------------|------|--|
| Dimension Limits | | MIN | NOM | MAX | |
| Contact Pitch | Е | 0.825 BSC | | | |
| Contact Pad Width (X4) | X1 | | | 0.65 | |
| Contact Pad Width (X2) | X2 | | | 0.25 | |
| Contact Pad Length (X6) | Υ | | | 0.85 | |
| Contact Pad Spacing | С | | 1.45 | | |
| Space Between Contacts (X4) | G1 | 0.38 | | | |
| Space Between Contacts (X3) | G2 | 0.60 | | | |

Notes:

Note:

- Dimensioning and tolerancing per ASME Y14.5M
 BSC: Basic Dimension. Theoretically exact value shown without tolerances.
- 2. For best soldering results, thermal vias, if used, should be filled or tented to avoid solder loss during reflow process

Microchip Technology Drawing C04-3005A

NOTES:

APPENDIX A: REVISION HISTORY

Revision A (September 2016)

- Converted Micrel data sheet DSC2311 to Microchip DS20005611A.
- Minor text changes throughout.
- · Package name updated to VDFN.

NOTES:

PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, contact your local Microchip representative or sales office.

PART NO. -Rxxxx **Device** Package Temperature Stability Frequency Package

Device: DSC2311: Crystal-less Configurable Two-Output Clock

Generator

Package: 6-LEAD 2.5 mm x 2.0 mm VDFN Κ

-20°C to +70°C (Extended Commercial) Temperature

Range:

-40°C to +85°C (Industrial) -40°C to +105°C (Extended Industrial) M -40°C to +125°C (Automotive)

Stability: ±50 ppm

Frequency: Rxxxx Custom Frequency Code

Packing Option: Blank Tube Tape & Reel

Output Clock Frequencies

Output frequencies are factory-configured to individual customer and product requirements, subject to output control and divider limitations. Contact sales with your custom frequency needs.

| Frequency Code | F _{OUT1} (MHz) | F _{OUT2} (MHz) |
|----------------|-------------------------|-------------------------|
| R0001 | 127 | 127 |
| R0002 | 25 | 125 |

Examples:

DSC2311KE1-RxxxxT: Crystal-less Configurable

Two-Output Clock Generator, 6-LD VDFN, Extended Commercial Temp. Range, ±50 ppm Stability, Custom Frequency (F_{OUT1} and

F_{OUT2}), Tape & Reel

DSC2311KM2-Rxxxx: Crystal-less Configurable

Two-Output Clock Generator, 6-LD VDFN, Automotive Temp. Range, ±25 ppm Stability, Custom Frequency (F_{OUT1} and F_{OUT2}), Tube

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